

DERWENT-ACC-NO: 1998-031140

DERWENT-WEEK: 200029

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TITLE: Adhesive-free adhesion between polymeric  
surfaces using free radical polymerisation proceeds to modify  
the first and the second substrates and contact them in  
liquid medium

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PATENT-ASSIGNEE: NAT SCI COUNCIL[NASCN]

PRIORITY-DATA: 1996TW-115919 (December 23, 1996)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
TW 314546 A	September 1, 1997	ZH
<b>JP 10182851 A</b>	July 7, 1998	JA
JP 3044206 B2	May 22, 2000	JA

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
TW 314546A December 23, 1996	N/A	1996TW-115919
JP 10182851A December 4, 1997	N/A	1997JP-334147
JP 3044206B2 December 4, 1997	Previous Publ	1997JP-334147

INT-CL-CURRENT:

TYPE	IPC	DATE
CIPP	C08J5/12	20060101

ABSTRACTED-PUB-NO: TW 314546 A

BASIC-ABSTRACT:

A manufacturing method for adhesion between polymeric substrate

includes the following steps: (a) Firstly functional monomer with free radical polymerization proceeds surface graft polymerization to modify the surface of first polymeric substrates. (b) Secondly functional monomer with free radical polymerization proceeds surface graft polymerization to modify the surface of second polymeric substrates. (c) The surface of firstly and secondly modified polymeric substrates contacts each other under liquid medium. (d) Keep contact for some time until liquid medium to be dry.

TITLE-TERMS: ADHESIVE FREE POLYMERISE SURFACE RADICAL PROCEED  
MODIFIED FIRST

SECOND SUBSTRATE CONTACT LIQUID MEDIUM

DERWENT-CLASS: A35

CPI-CODES: A10-C03A; A11-B09D; A11-C01D; A12-S06C1;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1]

018 ; P0000; L9999 L2802; H0088 H0011; L9999 L2573 L2506;

Polymer Index [1.2]

018 ; ND07; N9999 N5721\*R; N9999 N7192 N7023; Q9999 Q7818\*R;  
K9574

K9483; K9687 K9676; K9676\*R; K9712 K9676;

Polymer Index [1.3]

018 ; C999 C088\*R C000; C999 C271;

SECONDARY-ACC-NO:

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